

Title: 2nd Tools in Process workshop (TiP 2013)

Workshop Organizers:

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Goal of the Workshop:

The complexity of embedded systems and their architectures is growing rapidly. This is due to market demand for more functionality and to the non-stopping evolution/improvement of the available technologies, which are being integrated together in new and innovative ways. This complexity growth demands improved tool support, which are capable of providing adequate coverage of the embedded systems design and development process.

At an individual tool level, specialized tools are available to cover novel necessary features of modern devices and provide support for most of the large tool frameworks phases of the design in a unitary environment. On the next level, the main solutions available for dealing with the current complexity challenges are addressed by integration frameworks and tool-chains that combine/integrate different tools together covering the whole embedded systems design and development process.

The second Tools in Process workshop intend to gather and illustrate experiences in tools development and utilization in the area of embedded systems design. Starting with requirements elicitation, and ending with post deployment situations, all design phases are of interest with respect to the tooling solutions.

Theme of the Workshop:

The theme of this workshop is Integration and tool interoperability. Today, it is not possible to cost-efficiently engineer high quality systems without an extensive use of different tools which work well together, covering as much as possible of the design process. Tool integration is a real challenge, and even more so when the tools are being used by engineering communities with different traditions and cultures.

Scope of the Workshop (Call-for-Papers):

Any submission whose content is relevant to the theme of tool interoperability and integration, but any submission whose subject matter is related to one of the following topics will be particularly welcome:

- New tool(s) developments / prototypes
- Experiences in tool utilization to address new challenges
- Tool integration strategies, technologies and solutions
- Success stories in the seamless integration of tool in the design process
- Tools in the support of long product life cycles

Program Committee:

- Martin Törnngren, Royal Institute of Technology, Sweden
- Birger Møller-Pedersen, University of Oslo, Norway
- Lubos Brim, Masaryk University, Czech Republic
- Joel Champeau, ENSTA-Bretagne, France
- Ali Koudri, Thales, France
- David Mulvaney, Loughborough University, UK
- Koen Bertels, Delft University of Technology, The Netherlands
- Stein-Erik Ellevseth, ABB Corporate Research, Norway
- Jose Manuel, IXION, Spain
- Radouane Oudrhiri, Systonomy, UK
- Oliver Sims, SELEX GALILEO, UK

Important Dates:

Deadline for paper submission: March 20th, 2013
Notification of acceptance: April 21th, 2013
Camera-ready due: May 5th, 2013

Submission:

Papers must be submitted electronically via the TiP 2013 Submission Page (<http://myreview.cs.iastate.edu/TIP2013>). The format of submitted papers should follow the guidelines for the IEEE conference proceedings. All papers will be carefully reviewed by at least three reviewers. Papers should be no more than 6 pages. Accepted papers will be published in the workshop proceedings of COMPSAC 2013, by the IEEE Computer Society Press. At least one of the authors of each accepted paper must register as a participant of the workshop and present the paper at the workshop, in order to have the paper published in the proceedings.

Expected number of workshop sessions:
2 sessions